



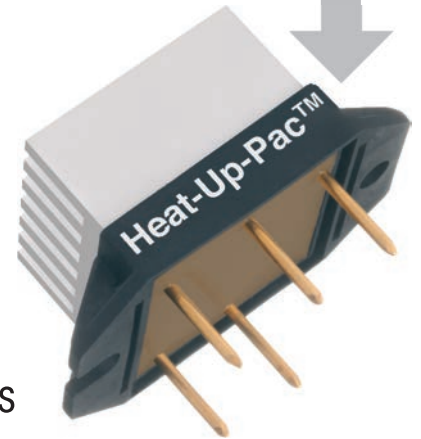
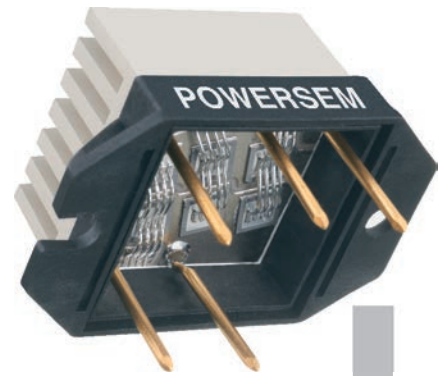
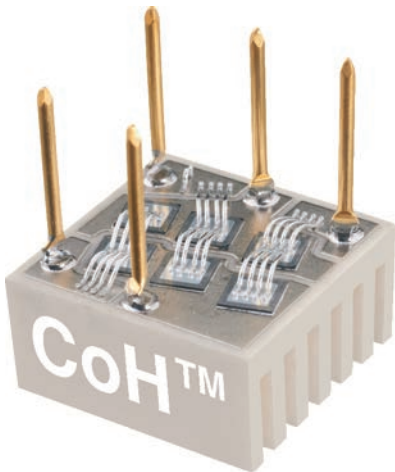
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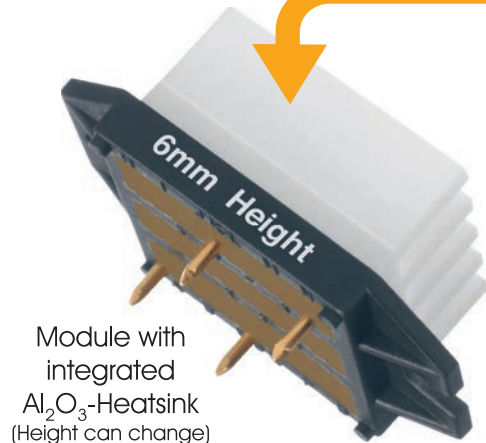


**NEW**

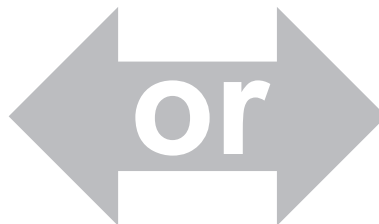
## Heat-Up-Pac™

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- Fast mounting of the Module
- For Si-, SiC-, GaN- and GaAs-Devices

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Module with integrated AlN-Heatsink (Height can change)

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**PCIM**  
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